2SJ146

Silicon P-Channel MOS FET

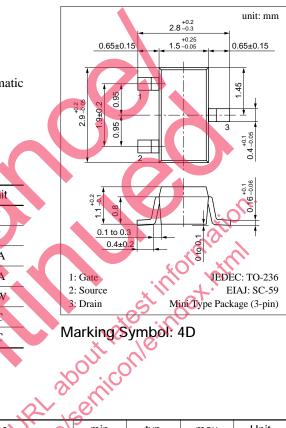
For switching

■ Features

- High-speed switching
- Mini-type package, allowing downsizing of the sets and automatic insertion through the tape/magazine packing.

■ Absolute Maximum Ratings (Ta = 25°C)

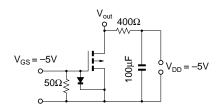
Parameter	Symbol	Ratings	Unit
Drain to Source breakdown voltage	V _{DSS}	-50	V
Gate to Source voltage	V_{GSO}	-8	V
Drain current	I_D	-100	mA
Max drain current	I_{DP}	-200	mA
Allowable power dissipation	$P_{\rm D}$	150	mW
Channel temperature	T_{ch}	150	°C
Storage temperature	T_{stg}	-55 to +150	°C

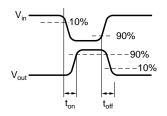


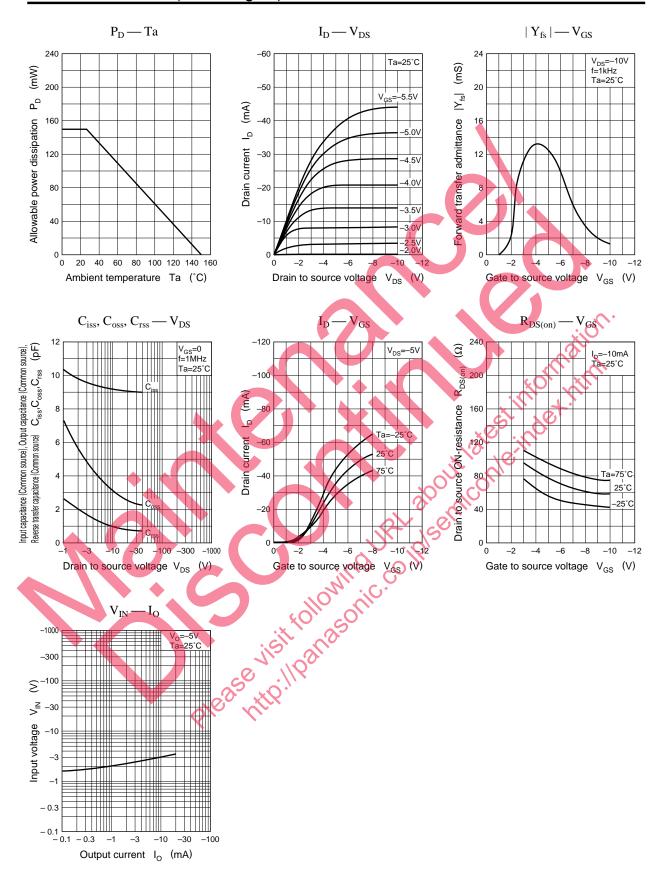
■ Electrical Characteristics (Ta = 25°C)

Parameter	Symbol	Conditions	min	typ	max	Unit
Drain to Source cut-off current	I _{DSS}	$V_{DS} = -30V, V_{GS} = 0$			-10	μA
Gate to Source leakage current	I _{GSS}	$V_{GS} = -8V, V_{DS} = 0$			-1	μA
Drain to Source breakdown voltage	V _{DSS}	$I_D = -100 \mu A, V_{GS} = 0$	-50			V
Gate threshold voltage	V _{th}	$V_{DS} = -5V, I_{D} = 100 \mu A$	-1.5		-3.5	V
Forward transfer admittance	Y _{fs}	$V_{DS} = -10V; I_{D} = -10\text{mA}, f = 1\text{kHz}$	8	13.5		mS
Drain to Source ON-resistance	R _{DS(on)}	$V_{GS} = +5V, I_D = -10mA$			150	Ω
Input capacitance (Common Source)	C _{iss}				13	pF
Output capacitance (Common Source)	Coss	$V_{DS} = -5V, V_{GS} = 0, f = 1MHz$			7	pF
Reverse transfer capacitance (Common Source)	C_{rss}				3	pF
Turn-on time	t _{on} *	$V_{DD} = -5V$, $V_{GS} = 0$ to $-5V$, $R_L = 400\Omega$			40	ns
Turn-off time	t _{off} *	$V_{DD} = -5V, V_{GS} = -5 \text{ to } 0V, R_L = 400\Omega$			60	ns

^{*} t_{on}, t_{off} measurement circuit







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